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April 2013

FDB12N50U

N-Channel UniFETTM Ultra FRFETTM MOSFET 500 V, 10 A, 800 m Ω

Features

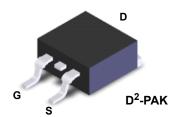
- $R_{DS(on)} = 650 \text{ m}\Omega \text{ (Typ.)} @ V_{GS} = 10 \text{ V, } I_D = 5 \text{ A}$
- Low Gate Charge (Typ. 21 nC)
- Low Crss (Typ. 11pF)
- · 100% Avalanche Tested
- · Improved dv/dt Capability
- · RoHS Compliant

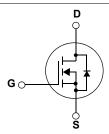
Applications

- · Lighting
- · Uninterruptible Power Supply
- · AC-DC Power Supply

Description

UniFETTM MOSFET is Fairchild Semiconductor[®]'s high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. UniFET Ultra FRFETTM MOSFET has much superior body diode reverse recovery performance. Its t_{rr} is less than 50nsec and the reverse dv/dt immunity is 20V/nsec while normal planar MOSFETs have over 200nsec and 4.5V/nsec respectively. Therefore UniFET Ultra FRFET MOSFET can remove additional component and improve system reliability in certain applications that require performance improvement of the MOSFET's body diode. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted*

Symbol	Parameter			FDB12N50U	Unit
V _{DSS}	Drain to Source Voltage			500	V
V _{GSS}	Gate to Source Voltage			±30	V
	Drain Current	- Continuous (T _C = 25°C)		10	۸
ID	Drain Current	- Continuous (T _C = 100°C)		6	A
I _{DM}	Drain Current	- Pulsed	(Note 1)	40	Α
E _{AS}	Single Pulsed Avalanche Energy (Note			456	mJ
I _{AR}	Avalanche Current		(Note 1)	10	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	16.5	mJ
dv/dt	Peak Diode Recovery dv/d	t	(Note 3)	20	V/ns
n	Dawer Dissination	(T _C = 25°C)		165	W
P_{D}	Power Dissipation	- Derate above 25°C		1.33	W/°C
T _J , T _{STG}	Operating and Storage Ten	nperature Range		-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C

Thermal Characteristics

Symbol	Parameter FDB12N50		Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.75	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	· C/VV

Package Marking and Ordering Information T_C = 25°C unless otherwise noted

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB12N50U	FDB12N50UTM_WS	D2-PAK	330mm	24mm	800

Electrical Characteristics

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu A$, $V_{GS} = 0V$, $T_J = 25^{\circ}C$	500	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C	-	0.7	-	V/°C
1	Zoro Coto Voltago Droin Current	V _{DS} = 500V, V _{GS} = 0V	-	-	25	
IDSS	Zero Gate Voltage Drain Current	$V_{DS} = 400V, T_C = 125^{\circ}C$	-	-	250	μА
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10V, I_D = 5A$	-	0.65	0.8	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40V, I_{D} = 5A$	ı	11	ı	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 25V, V _{GS} = 0V		1050	1395	pF
C _{oss}	Output Capacitance			140	190	pF
C _{rss}	Reverse Transfer Capacitance	- 1 - 11VII 12	-	11	17	pF
Q _{g(tot)}	Total Gate Charge at 10V		-	21	30	nC
Q _{gs}	Gate to Source Gate Charge	$V_{DS} = 400V, I_{D} = 10A$	-	6	-	nC
Q _{gd}	Gate to Drain "Miller" Charge	$V_{GS} = 10V$ (Note 4)	-	9	-	nC

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	35	80	ns
t _r	Turn-On Rise Time	$V_{DD} = 250V, I_{D} = 10A$		-	45	100	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 25\Omega$		-	60	130	ns
t _f	Turn-Off Fall Time		(Note 4)	-	35	80	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	10	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	40	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0V, I _{SD} = 12A		-	-	1.6	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _{SD} = 12A	-	60	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$	-	0.1	-	μС

- **Notes:**1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 9mH, I_{AS} = 10A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C
- 3. I $_{SD}$ \leq 10A, di/dt \leq 200A/ μ s, V_{DD} \leq BV $_{DSS}$, Starting T_{J} = 25°C
- 4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

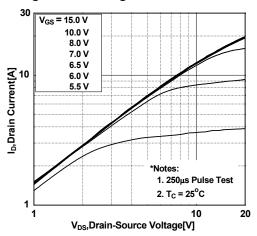


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

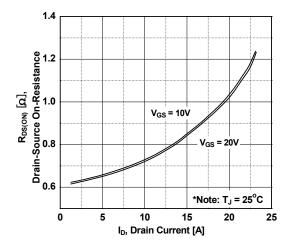


Figure 5. Capacitance Characteristics

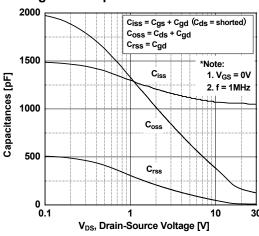


Figure 2. Transfer Characteristics

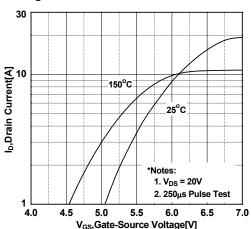


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

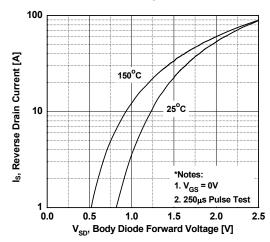
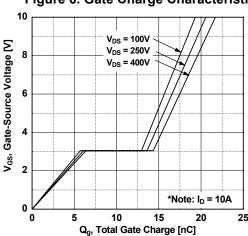
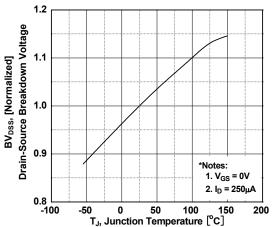


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature



T_J, Junction Temperature [°C]

Figure 9. Maximum Drain Current

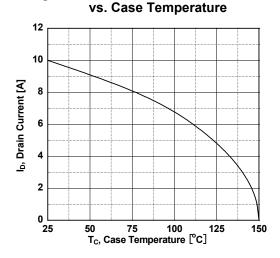


Figure 8. Maximum Safe Operating Area

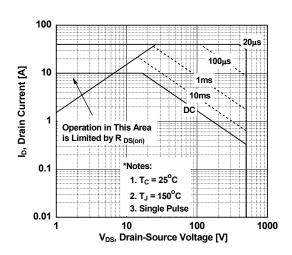
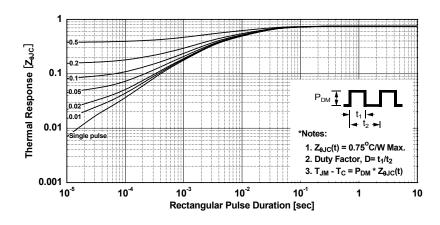
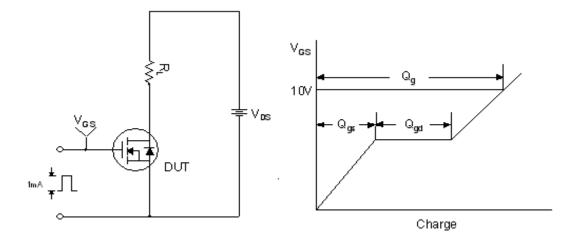


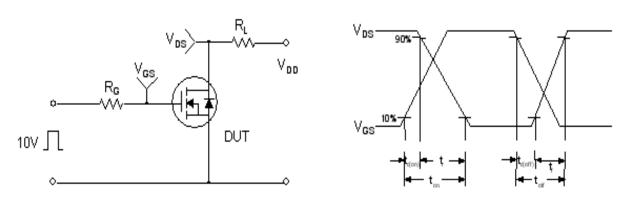
Figure 10. Transient Thermal Response Curve



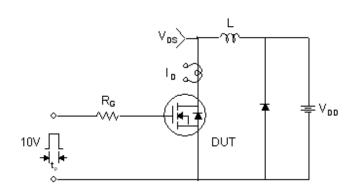
Gate Charge Test Circuit & Waveform

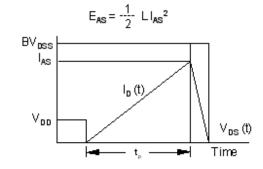


Resistive Switching Test Circuit & Waveforms

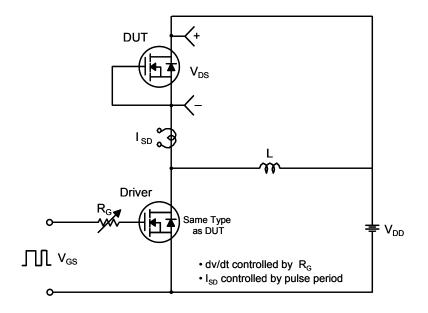


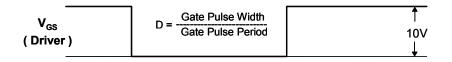
Unclamped Inductive Switching Test Circuit & Waveforms

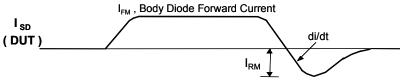




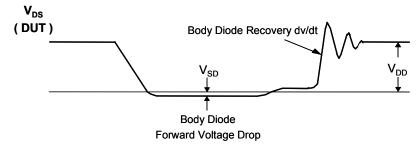
Peak Diode Recovery dv/dt Test Circuit & Waveforms





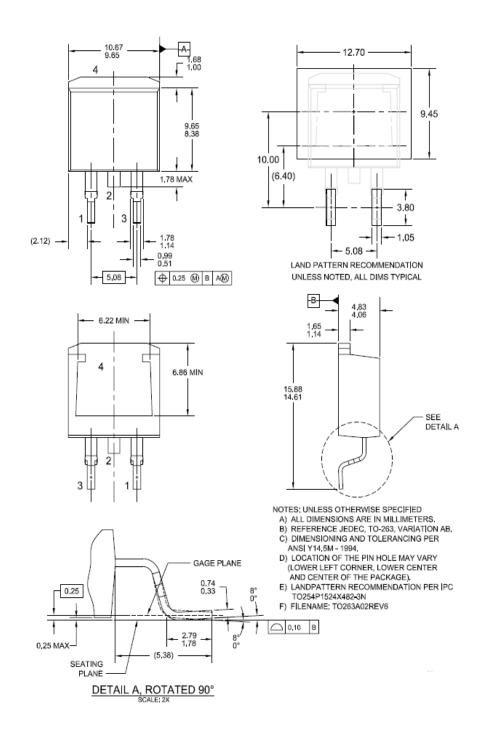


Body Diode Reverse Current



Mechanical Dimensions

D²PAK







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